

EMAP2007 -- **International Symposium on Electronic Materials and Packaging**

November 19-22, 2007

KAIST (Korea Advanced Institute of Science & Technology), Daejeon, Korea

You are invited to submit a paper for the EMAP2007. The EMAP2007 symposium is organized by KAIST in collaboration with the Center for Electronic Packaging Materials (CEPM). It is jointly sponsored by the IEEE CPMT Daejeon Chapter, IMAPS-Korea, Korea Society of Mechanical Engineers, Korea Society of Electric Engineers, and ASME Korea Section. The objective of this symposium is to create an international forum for the exchange, dissemination and discussion of state-of-the-art technologies and recent developments in electronic materials, packaging and assembly. Following the tremendous success in the last eight conferences in Singapore, Hong Kong, Korea, Taiwan, Malaysia and Japan, which were attended by delegates from more than 10 major countries, the ninth symposium will be held again at the KAIST campus at Daejeon Korea. So come and meet world-renowned authorities from the Asia-Pacific region, USA and Europe. Join us and get in touch with leading-edge electronics packaging technologies, and find out more about Korea's electronics packaging industries. In addition, short courses on current packaging trends and technological issues will be also offered. Papers are invited from industry participants as well as researchers from the academia and government research organizations.

Call for Papers (abstracts due **July 31**)

Major Topics of the Symposium:

- Advanced Electronic Packaging Technologies: WLP, Flip Chip, CSP, SIP, SOP, 3-D
- Packaging Materials and Processes: Lead-free Solders, Adhesives, Underfills, Encapsulants, PCBs
- Interconnect Technologies: Wire bonding, Fine Pitch, Micro via, Build-up Technologies
- Materials Characterization, Testing and Measurements: Electrical, Thermal, Chemical, Mechanical
- Package Design, Modeling and Simulation
- Sensors/Bio/MEMS Packaging
- Reliability and Failure Analysis: Interfacial Phenomena, Delamination, Moisture effects
- Polymers and Ceramics for Electronic Applications, Thin films/coatings, Metallization

Abstracts and Papers

A one-page 300-word abstract should be submitted to the Secretariat of the Symposium, describing the scope, contents and key points of the proposed paper. Instructions for preparing the full paper will be sent to the authors whose abstracts are accepted after review. Participants will be required to register upon notification of acceptance of their full papers. The detailed conference information will be announced later at the website, emap.kaist.ac.kr. If you have any questions, please send an e-mail to emap@kaist.ac.kr.

11th IEEE WORKSHOP ON **SIGNAL PROPAGATION ON INTERCONNECTS**

May 13-16, 2007

"Hotel Portofino Kulm"

Ruta di Camogli (Genova), Italy

Sponsored by
the IEEE Computer Society - Test Technology Technical Council (TTTC) and by
the IEEE Components, Packaging, and Manufacturing Technology (CPMT) Society

Deadlines

- Paper Submission: February 28, 2007
- Notification of Acceptance: March 31, 2007
- Guaranteed hotel reservations: April 5, 2007
- Advance registration: April 14, 2007

Paper Submission

Perspective Authors should send (by e-mail only) a formatted two-page or four-page paper to the Program Chair (ivano.maio@polito.it) by February 28, 2007. Please see the submission instruction on our website: www.spi.uni-hannover.de

CALL FOR PAPERS

The workshop covers the areas of interconnections and packaging modeling, simulation, design, measurement and testing at chip, board, and system levels.

It includes but is not limited to the following topics:

- Delta-I Noise
- Broadband Measurement Techniques and Theory
- Coupling Effects on Interconnects
- Determination of Characteristic Parameters
- Field Theory
- Ground Bounce
- Guided Waves on Interconnects
- Measurement, Modeling, and Simulation of Package Interconnects
- Non-Linear Modeling and Analysis
- Propagation Characteristics on Signal and Ground Lines
- Radiation and Interference
- Simulation Techniques for 2- and 3-dimensional Interconnect Structures
- Substrate Influence on Signal Propagation
- Interconnects and Testing
- Mixed Signal Test
- Optical Interconnects: Design and Test

visit www.spi.uni-hannover.de